

A 1.5V, 1.5GHz CMOS Low Noise Amplifier

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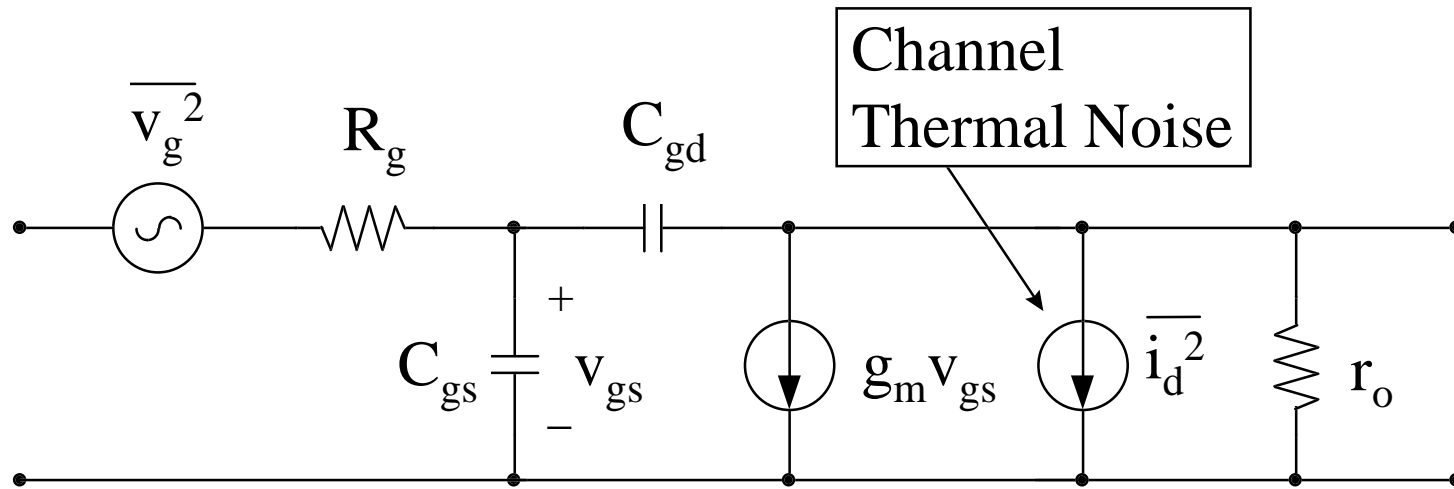


Outline

- *LNA Architecture / RF Noise*
- Experimental Results
- Summary and Conclusions



Simple CMOS Noise Model



- Channel thermal noise is dominant.

$$\overline{i_d^2} = 4kTB\gamma g_{d0}$$

- Gate resistance minimized by good layout.

Channel Thermal Noise

- Current HSPICE Implementation:

$$\overline{i_d^2} = \frac{8}{3} kTB g_m \quad (\text{NLEV} < 3)$$

$$\overline{i_d^2} = \frac{8}{3} kTB \cdot K' (V_{gs} - V_T) \frac{1 + a + a^2}{1 + a} GDSNOI \quad (\text{NLEV} = 3)$$

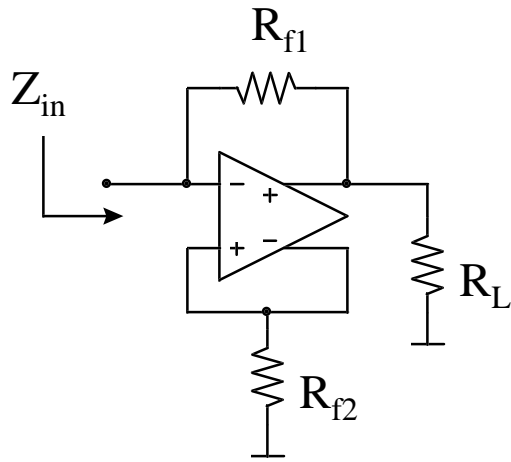
$$a = 1 - \frac{V_{ds}}{V_{dsat}}$$

- BSIM-3 Implementation:

$$\overline{i_d^2} = \frac{4kT\mu_{eff}}{L_{eff}^2} |Q_{inv}|$$



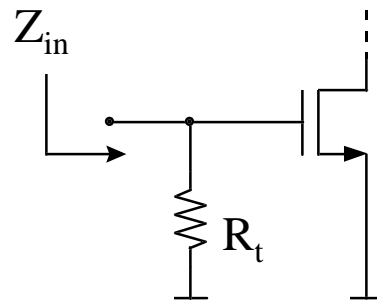
How To Get 50Ω



Dual Feedback

$$Z_{in} = \sqrt{R_{f1} R_{f2}}$$

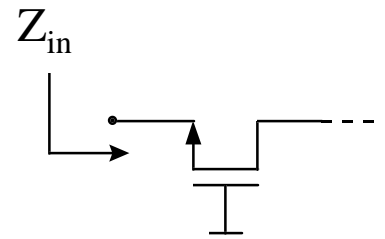
Need high gain.
Stability problems.



Resistive Termination

$$Z_{in} = R_t$$

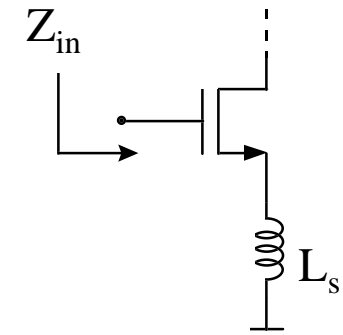
Poor NF.



$1/g_m$ Termination

$$Z_{in} = \frac{1}{g_m}$$

NF > 3dB
($\gamma > 1$)



Inductive Degeneration

$$\text{Re}[Z_{in}] = \frac{g_m}{C_{gs}} L_s$$

Narrowband.

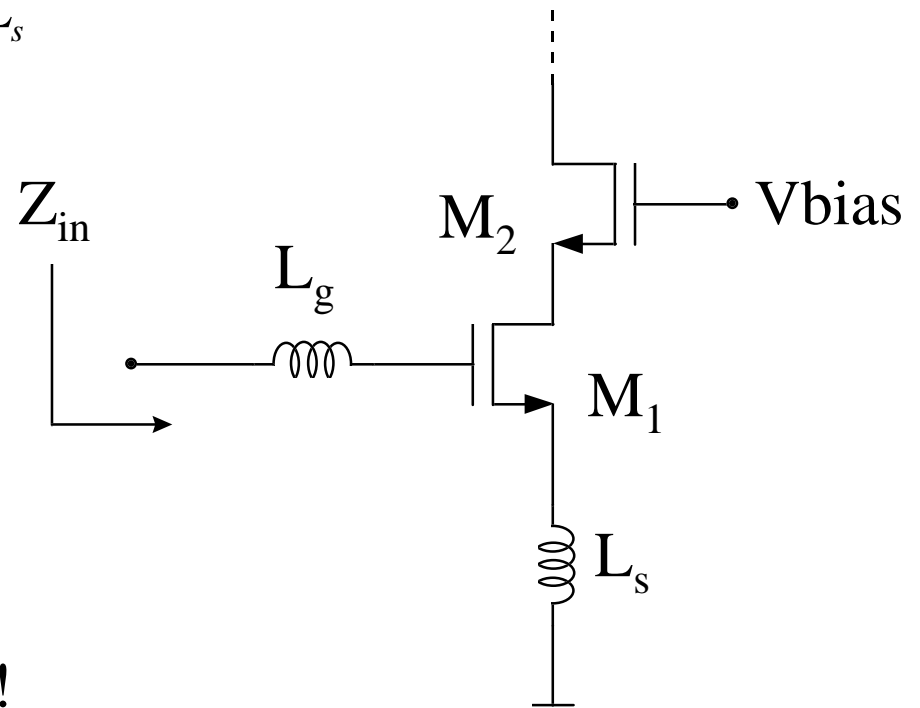


LNA Input Stage

$$Z_{in} = s(L_s + L_g) + \frac{1}{sC_{gs}} + \left(\frac{g_m}{C_{gs}}\right)L_s \approx \omega_T L_s$$

$$\begin{aligned} G_{m,eff} &= g_{m1} Q_{in} = \frac{g_{m1}}{\omega C_{gs} (R_s + \omega_T L_s)} \\ &= \frac{\omega_T}{\omega R_s \left(1 + \frac{\omega_T L_s}{R_s}\right)} = \frac{\omega_T}{2\omega R_s} \end{aligned}$$

Note: $G_{m,eff}$ is independent of g_{m1} !



Noise Factor

A common form

$$F = 1 + \frac{R_l}{R_s} + \frac{R_g}{R_s} + \frac{\gamma g_{d0} R_s \omega^2 C_{gs}^2}{g_m^2}$$

A better form

$$F = 1 + \frac{R_l}{R_s} + \frac{R_g}{R_s} + \gamma g_{d0} R_s \left(\frac{\omega}{\omega_T} \right)^2$$

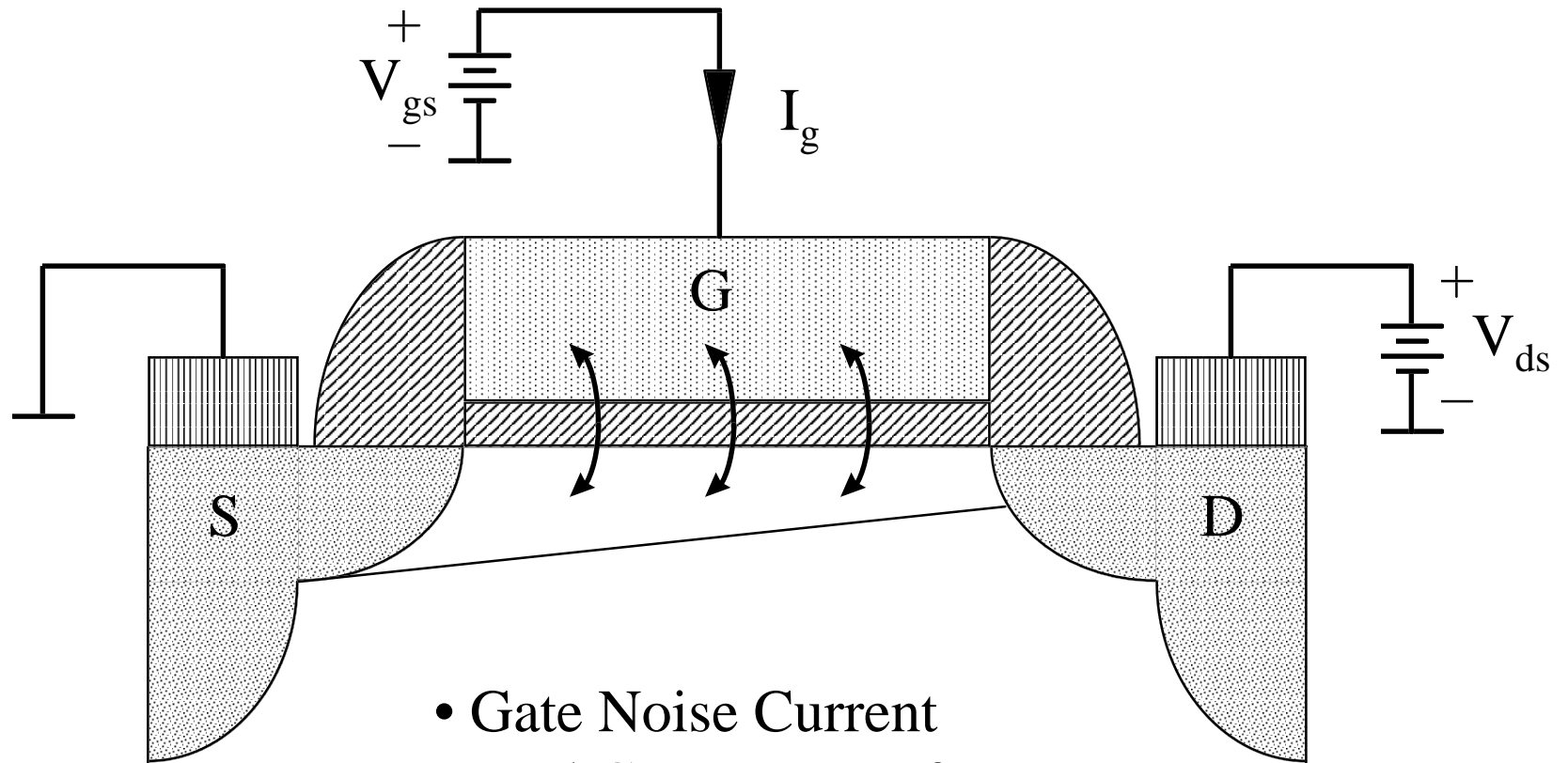
- Reducing g_{d0} , Increasing Q_{in} lowers F!
- Achieving low F involves linearity tradeoff.

$$|V_{gs}| = Q_{in} |V_s|$$

- Technology Scaling is Key.
- Problem : *The Free Lunch Principle*

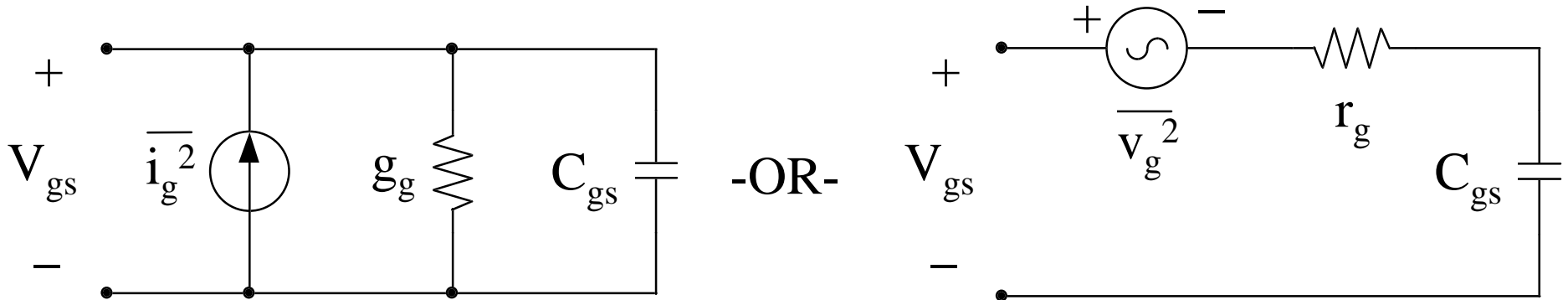


Induced Gate Effects



- Gate Noise Current
- Real Component of Z_g

Equivalent Gate Circuit



$$\overline{i_g^2} = 4kTB\delta g_g \quad g_g = \frac{1}{5} \frac{\omega^2 C_{gs}^2}{g_{d0}}$$

$$\overline{v_g^2} = 4kTB\delta r_g \quad r_g = \frac{1}{5g_{d0}}$$

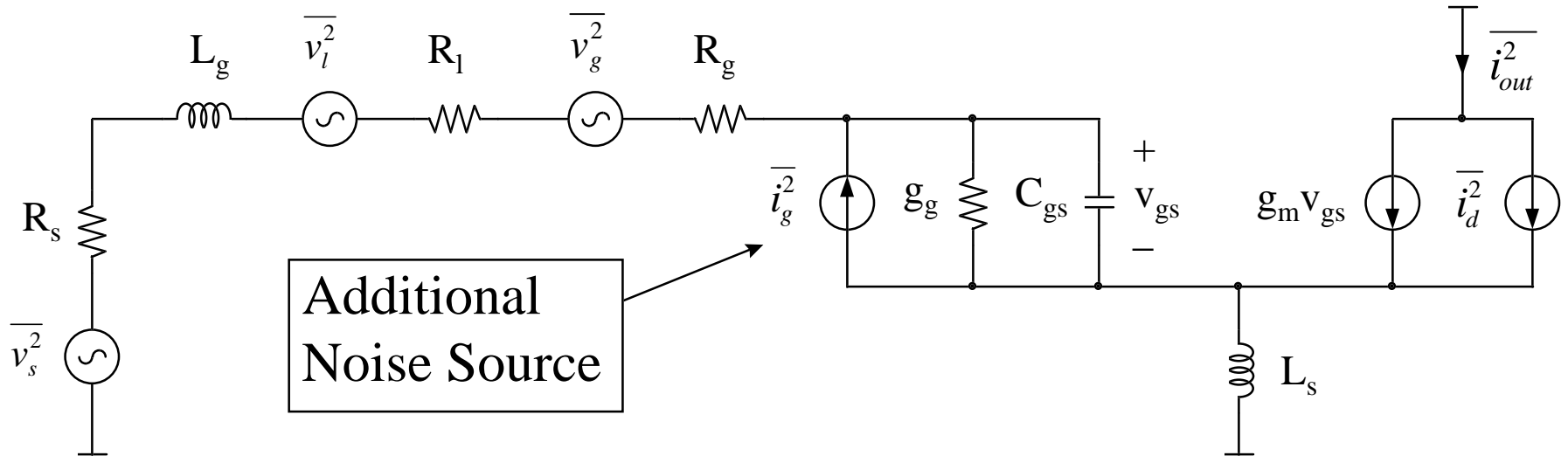
“Blue” Noise

- δ ($\sim 4/3$) modified by hot electron effects
- $\overline{i_g^2}$ partially correlated with $\overline{i_d^2}$ ($c = 0.395j$)
- $\overline{i_g^2}$ and g_g not modeled in HSPICE

“White” Noise



Revised Noise Factor



$$F = 1 + \frac{R_l}{R_s} + \frac{R_g}{R_s} + \gamma g_{d0} R_s \left(\frac{\omega}{\omega_T} \right)^2 \left\{ 1 + 2 \sqrt{\frac{\delta \alpha^2}{5\gamma}} Q_L |c| + \frac{\delta \alpha^2}{5\gamma} [1 + Q_L^2] \right\}$$

(At Resonance)



Noise Factor Terms

$$F = 1 + \frac{R_l}{R_s} + \frac{R_g}{R_s} + \gamma g_{d0} R_s \left(\frac{\omega}{\omega_T} \right)^2 \left\{ 1 + 2 \sqrt{\frac{\delta \alpha^2}{5\gamma}} Q_L |c| + \frac{\delta \alpha^2}{5\gamma} [1 + Q_L^2] \right\}$$

$$Q_L = \frac{\omega(L_s + L_g)}{R_s} = \frac{1}{\omega R_s C_{gs}} \approx 2 * Q_{in}$$

Q of the Input Circuit

$$\alpha = \frac{g_m}{g_{d0}} \leq 1$$

Decreases with shorter channels

$$c = \frac{\overline{i_g i_d^*}}{\sqrt{i_g^2 i_d^2}} = 0.395 j$$

Gate / Drain Correlation Factor



Minimum Noise Factor

Take $\frac{\partial F}{\partial W_{M1}} = 0$ to find the condition for minimum F:

$$Q_{L,opt} = \sqrt{1 + \frac{5\gamma}{\delta\alpha^2}} \geq 1.87 \quad \leftarrow \text{Long Channel Values}$$

$$F_{\min} = 1 + \sqrt{\frac{4}{5} \delta\gamma} \left(\frac{\omega}{\omega_T} \right) \left\{ |c| + \sqrt{1 + \frac{\delta\alpha^2}{5\gamma}} \right\} \geq 1 + 1.33 \left(\frac{\omega}{\omega_T} \right)$$

Note: Worst-Case $F_{\min} = 4$ (6dB) when $g_m = g_g$.



Architecture / Noise Summary

- MOS Device has gate current noise in addition to drain current noise. ➔ Optimum Z_s exists.
- Optimum Q_{in} relatively large. ➔ Power savings *and* lower F by reducing W_{M1} for $Q_{in} < Q_{opt}$.
- HSPICE models of MOS noise are inadequate.
 - Induced gate effects are not modeled at all.
 - Hot Electron effects influence the noise power spectral density of channel-related noise sources.

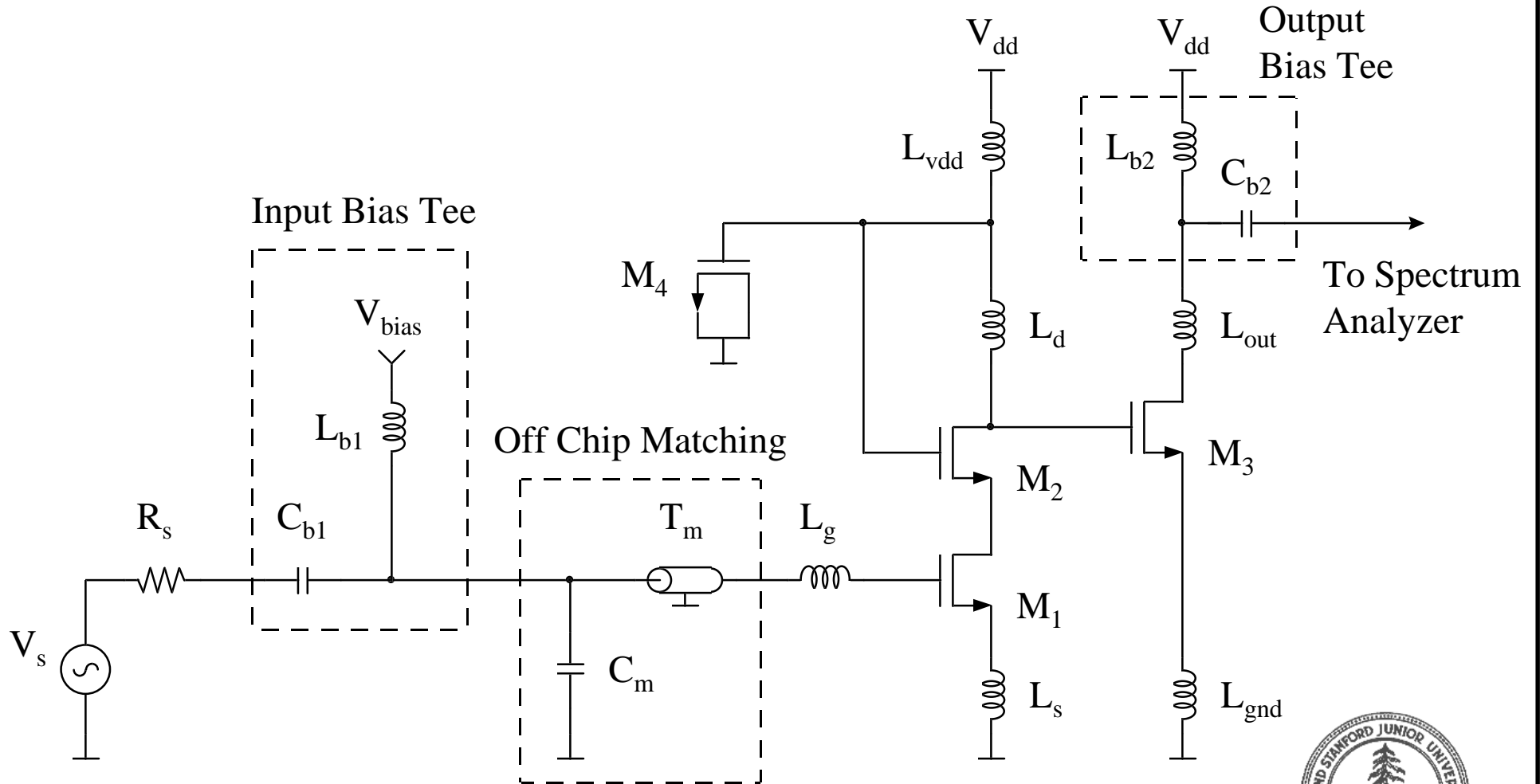


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Complete LNA Schematic

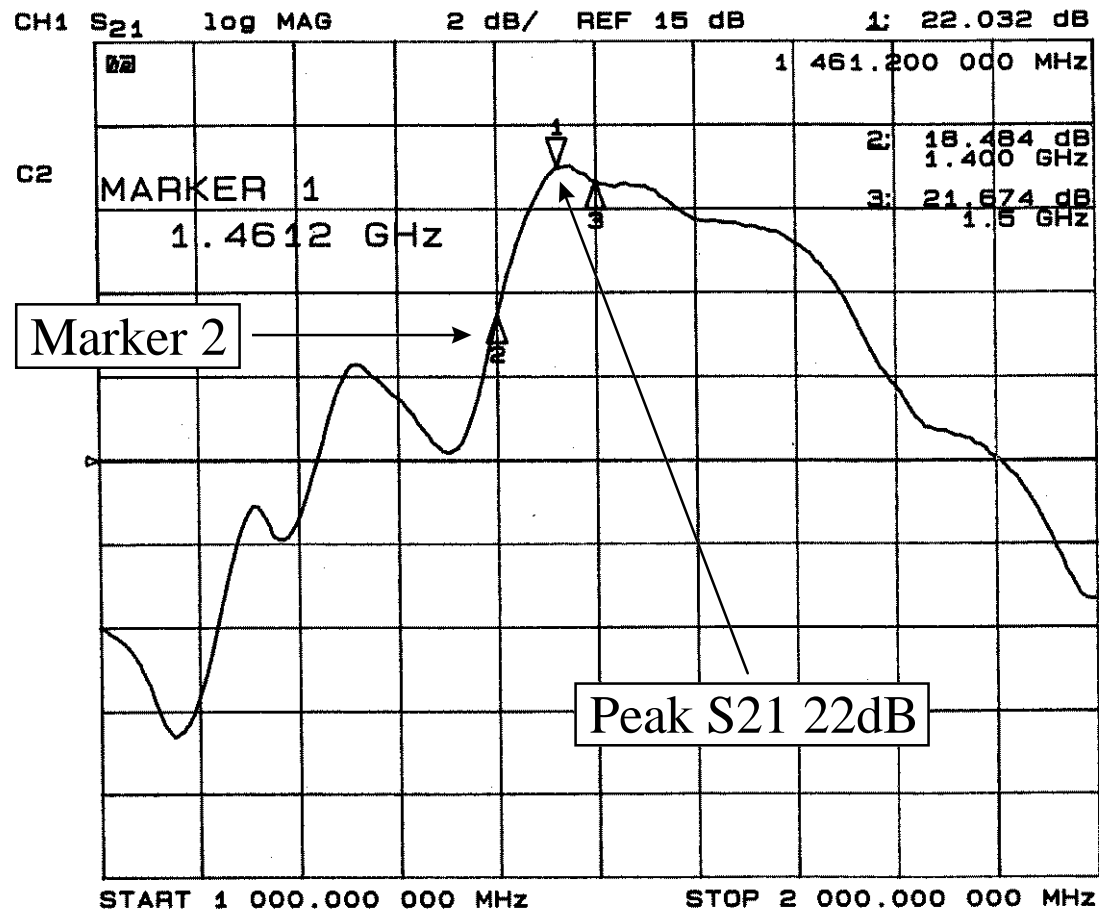


Die Photo

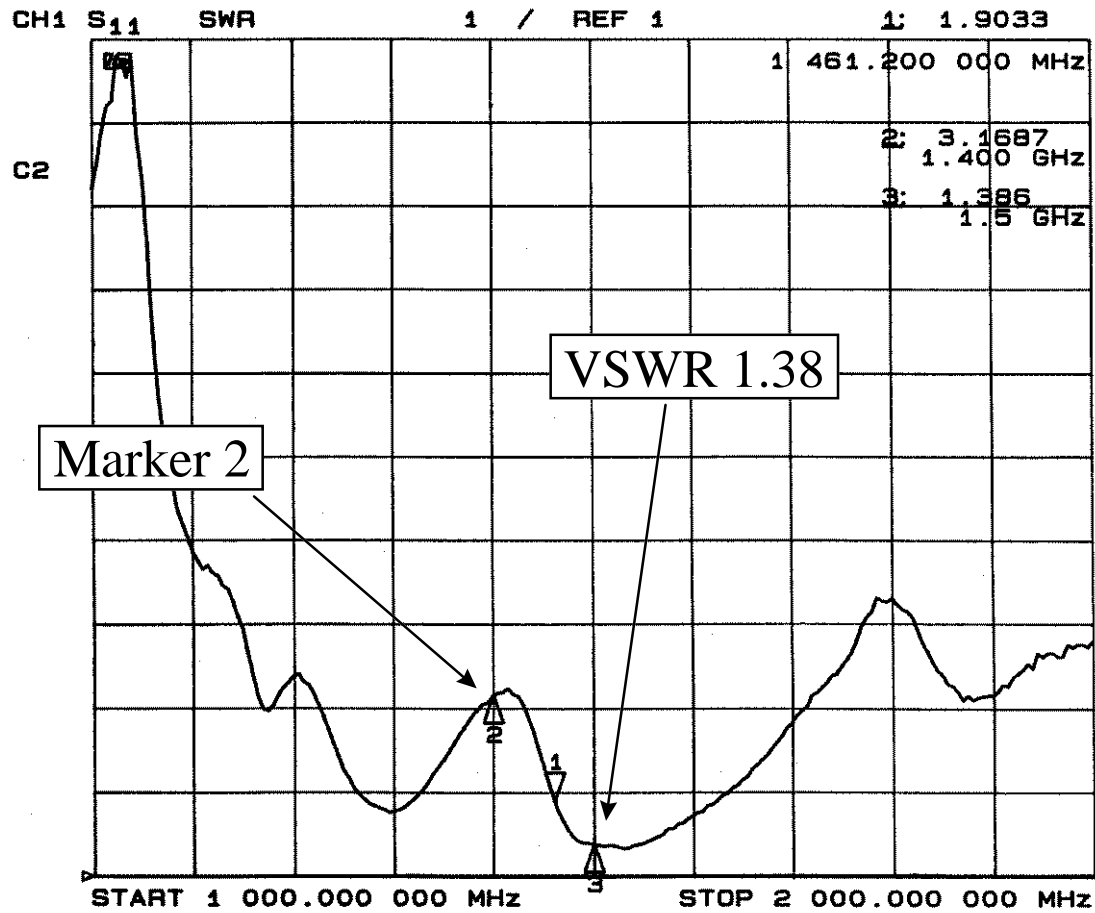
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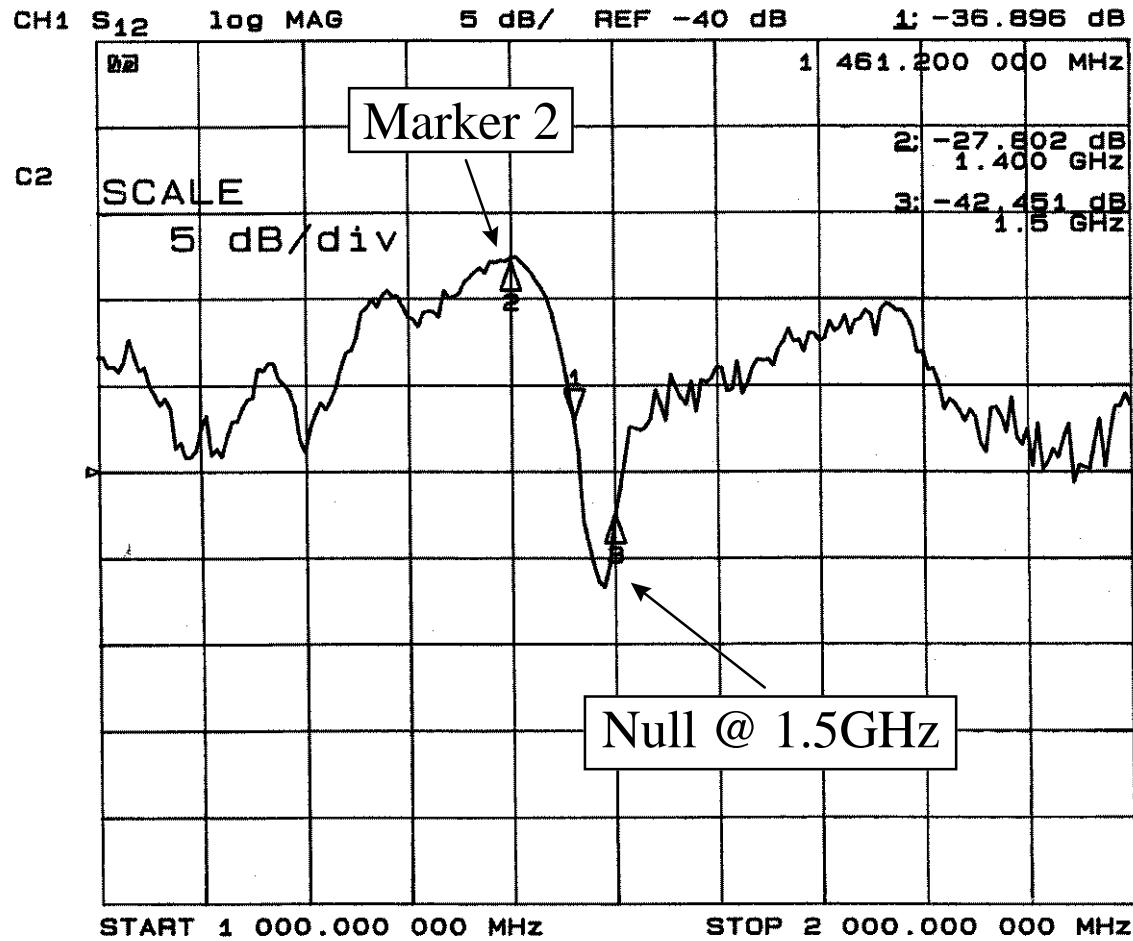
S21



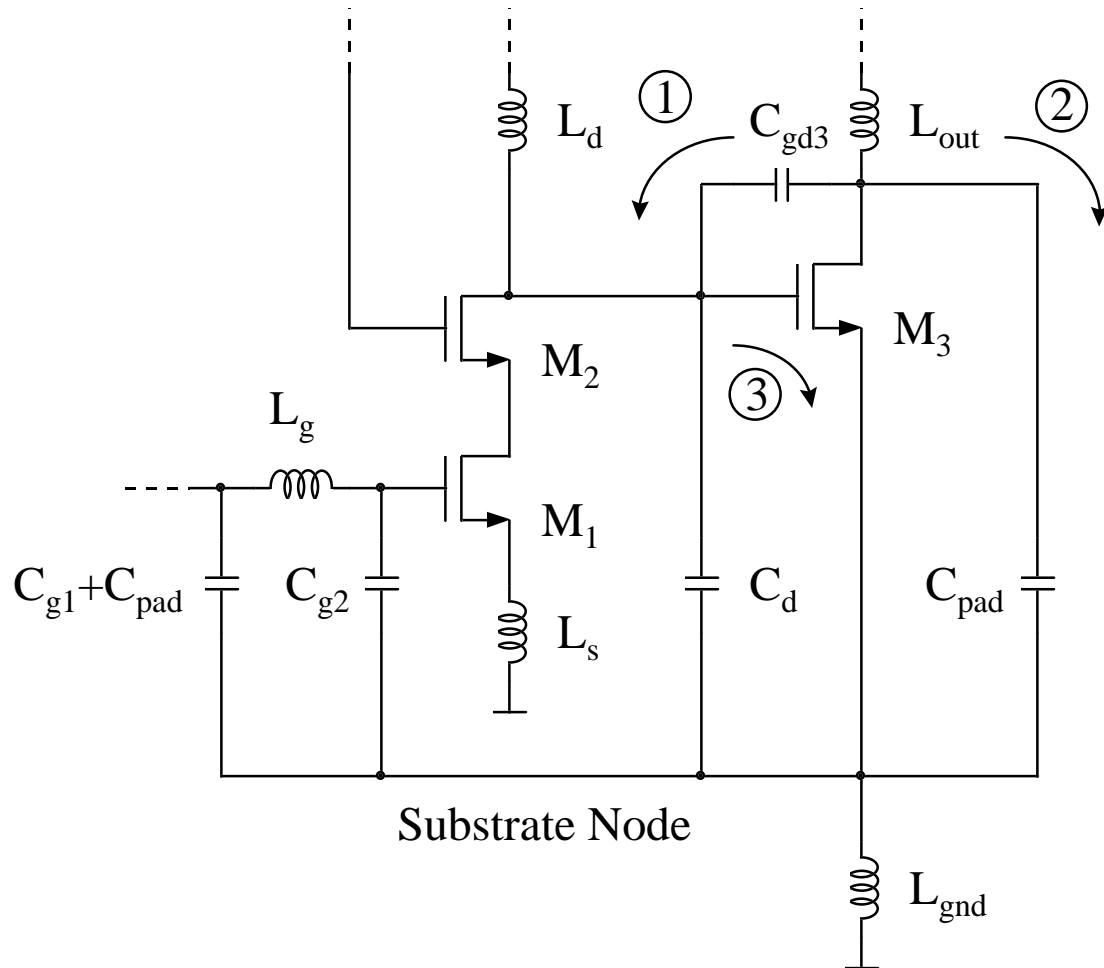
S11



S12

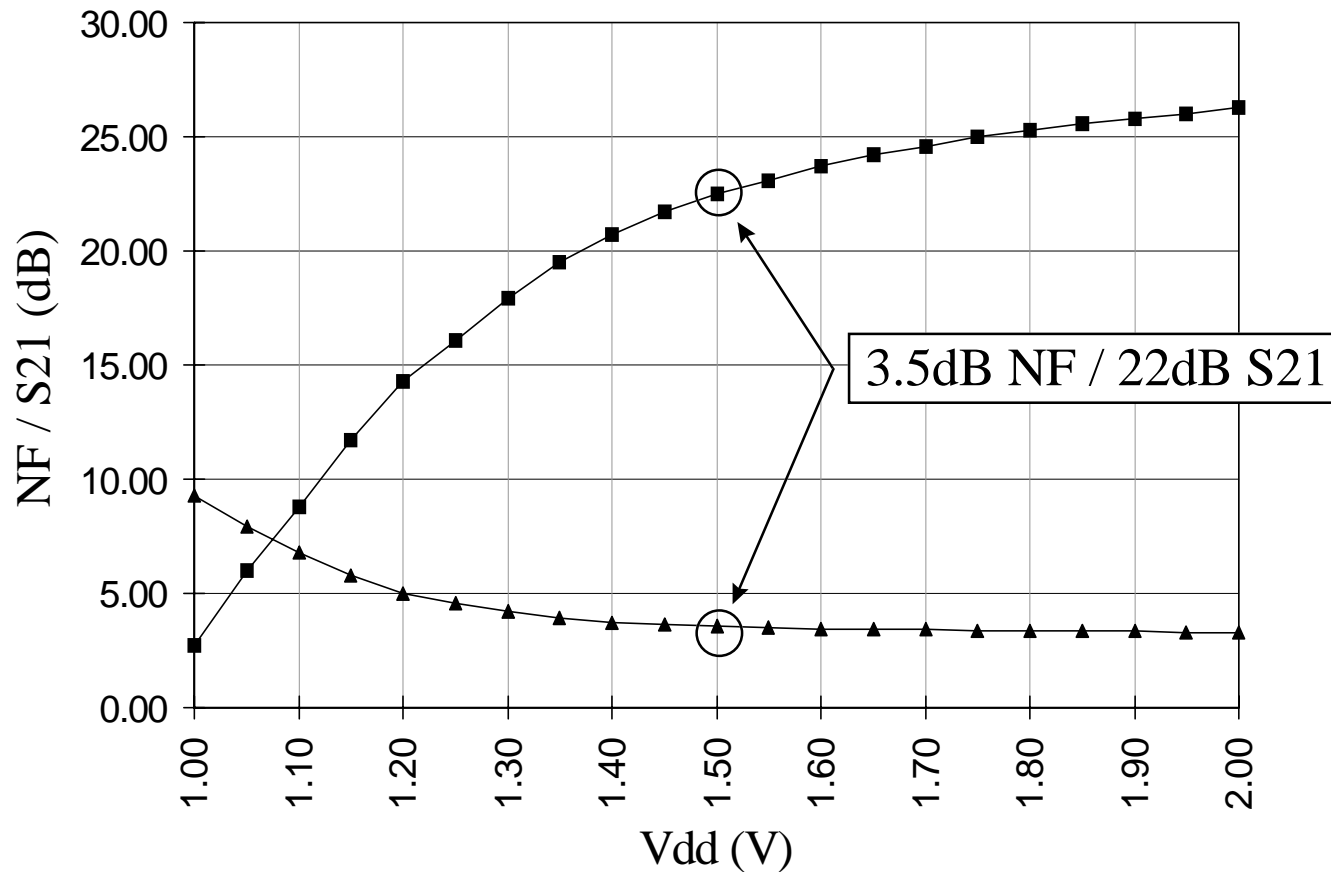


Reverse Isolation

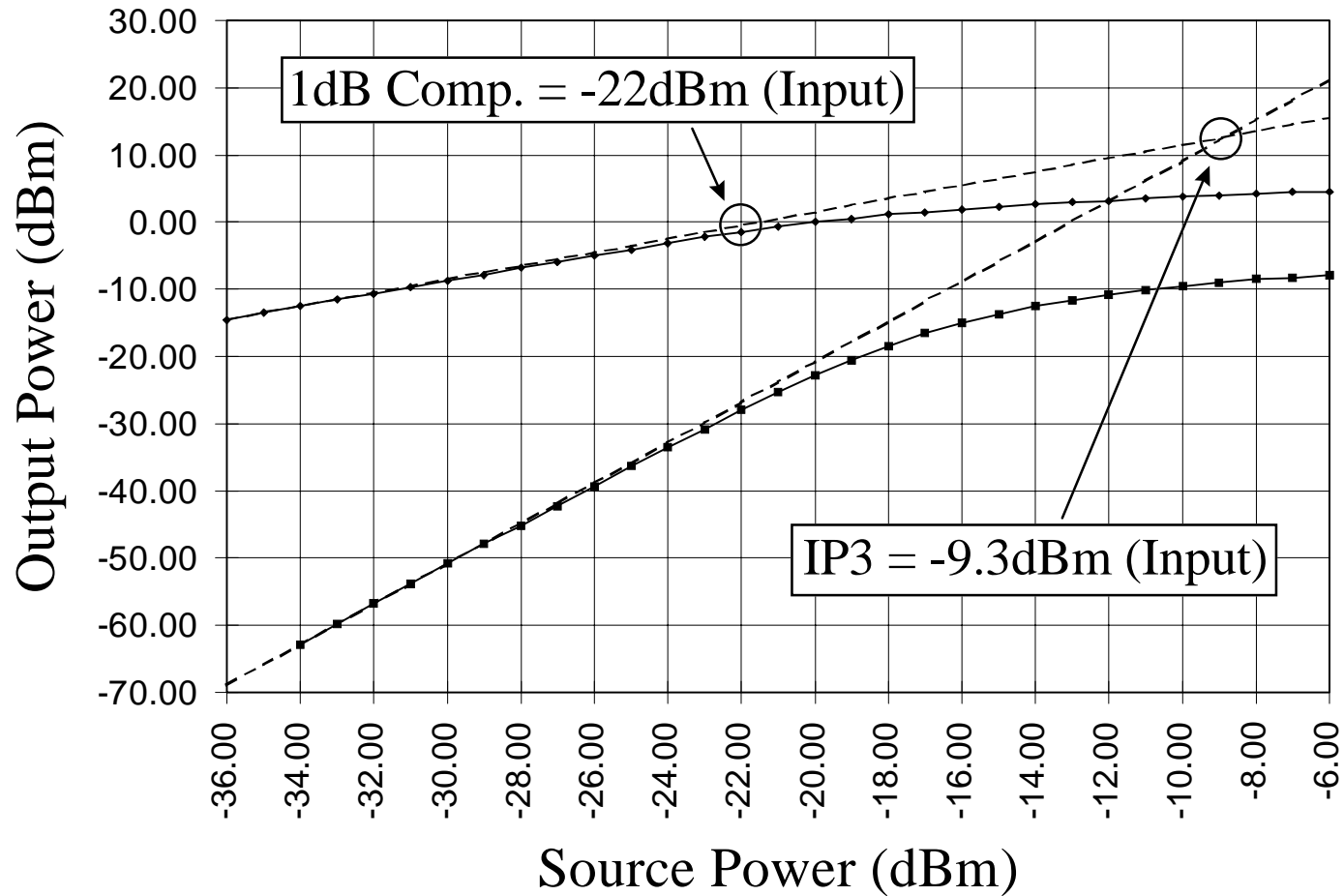


- Substrate tied to lowest inductance signal ground.
- Parasitic capacitances from spiral inductors and pads degrade reverse isolation.
- Simulation with parasitics shows null in S_{12} as seen in experimental data.

Noise Figure / S21 vs. Vdd



Linearity - IP3



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Performance Summary

Frequency	1.5GHz
Noise Figure	3.5dB
S21	22dB
IP3 (Input)	-9.3dBm
1dB Compression (Input)	-22dBm
Supply Voltage	1.5V
Power Dissipation	30mW
First Stage	7.5mW
Technology	0.6 μ m CMOS
Die Area	0.12 mm ²



Conclusions

- CMOS is suitable for low noise above 1GHz.
- 3.5dB NF is lowest to date for CMOS above 1GHz.
- 1dB NF can be expected with current generation.
- Current CMOS noise models, as in HSPICE, are inadequate for accurate simulation of RF noise.
 - Significant noise contributors are *absent* from the models.
 - Short channel effects have not been properly accounted for.
 - More research is required.



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